

SOLDER CONNECTION

Email: sales@solderconnection.co.uk | Tel: +44(0)1291 624 400

Issue 1 - 05/03/21

Technical Bulletin

TSC PURALLOY® 60/40 SOLDER ALLOY

DESCRIPTION

TSC PURALLOY[®] 60/40 solder alloy is manufactured using a proprietary process which greatly reduces any dross inclusions and provides a highly pure, free flowing alloy which in turn reduces the risk of bridging and solder skips during wave and selective soldering.

TSC PURALLOY® 60/40 solder alloy is available in 1 kg Bars, 3kg Ingots and Feed Wire. Chunks are also available to assist in new pot fills on request.

Product Features & Benefits

- Liquidus range 183°C 190°C
- Low Viscosity, high mobility
- Ultra low impurity levels.
- Refined grain structure.
- Meets IPC J-STD -006

TYPICAL COMPOSITION

Typical Alloy Composition

Sn: 60.0 Pb: 40.0

MELTING TEMPERATURE RANGE

Typical Melting Temperature

183°C -190°C

TECHNICAL SPECIFICATIONS

The following indicates the alloy and impurity limits for TSC PURALLOY® 60/40 Solder Alloy in relation to J-STD-006C.

ELEMENT	TSC 60/40	J-STD-006C
Sn	*59.5 -60.5	59.5 -60.5
Pb	Balance	Balance
Sb	0.20 max	0.20 max
Cu	0.08 max	0.08 max
Zn	0.003 max	0.003 max
Fe	0.02 max	0.02 max
As	0.03 max	0.03 max
Ni	0.01 max	0.01 max
Bi	0.10 max	0.10 max
Cd	0.002 max	0.002 max
Ag	0.10 max	0.10 max
Al	0.005 max	0.005 max
In	0.10 max	0.10 max
Au	0.05 max	0.05 max

All figures are % by weight

HANDLING & STORAGE

Indefinite shelf life applies to solid solder. For other product categories, refer to those specific TDSs. Consult 60/40 MSDS for additional handling procedures and precautions.

HEALTH & SAFETY

Use with adequate ventilation and proper personal protective equipment. Refer to the accompanying Safety Data Sheet for any specific emergency information. Do not dispose of any hazardous materials in non-approved containers.

The information contained herein is based on data considered accurate and is offered at no charge. No warranty is expressed or implied regarding the accuracy of this data. Liability is expressly disclaimed for any loss or injury arising out of the use of this information or the use of the materials designated.